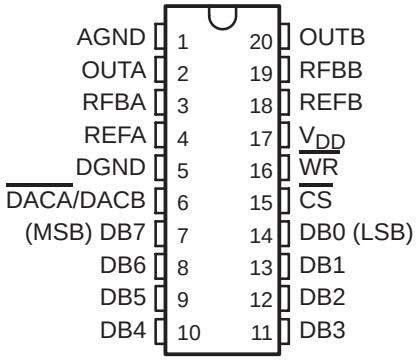
- **Easy Microprocessor Interface**
- **On-Chip Data Latches**
- **Digital Inputs Are TTL-Compatible With 10.8-V to 15.75-V Power Supply**
- **Monotonic Over the Entire A/D Conversion Range**
- **Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320**
- **CMOS Technology**

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2 LSB
Power Dissipation	20 mW
Settling Time	100 ns
Propagation Delay Time	80 ns

DW OR N PACKAGE
(TOP VIEW)



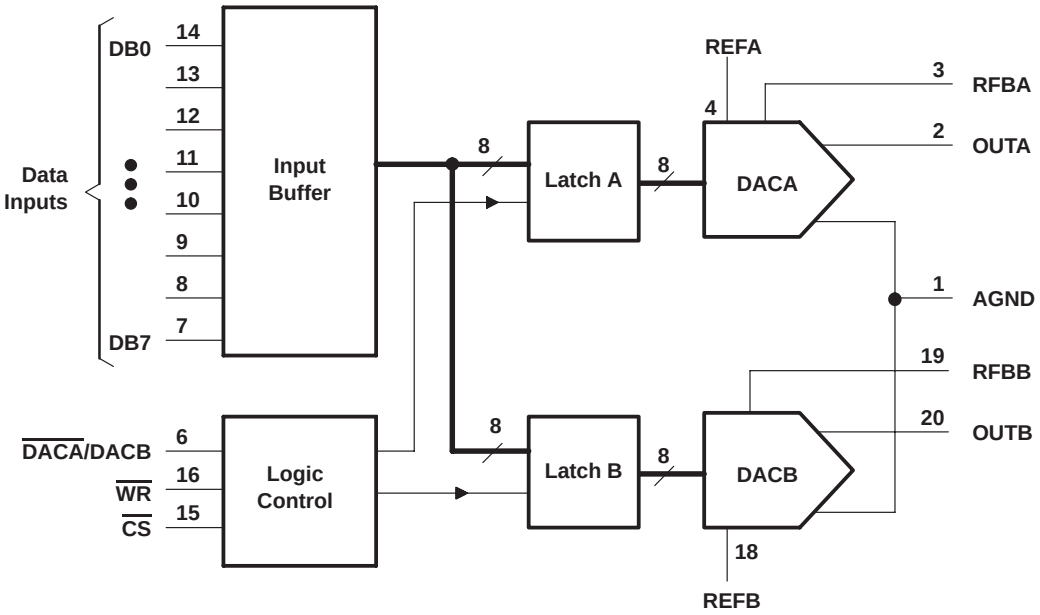
description

The TLC7628C is a dual, 8-bit, digital-to-analog converter (DAC) designed with separate on-chip data latches and featuring exceptionally close DAC-to-DAC matching. Data are transferred to either of the two DAC data latches through a common, 8-bit input port. Control input $\overline{\text{DACA}}$/DACB determines which DAC is loaded. The load cycle of this device is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

The TLC7628C operates from a 10.8-V to 15.75-V power supply and is TTL-compatible over this range. 2- or 4-quadrant multiplying makes this device a sound choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7628C is characterized for operation from 0°C to +70°C.

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (to AGND or DGND) . . . . . −0.3 V to 17 V
Voltage between AGND and DGND . . . . . V_{DD}
Input voltage range, V_I (to DGND) . . . . . −0.3 V to V_{DD} + 0.3 V
Reference voltage range, V_{refA} or V_{refB} (to AGND) . . . . . ±25 V
Feedback voltage range, V_{RFBA} or V_{RFBB} (to AGND) . . . . . ±25 V
Output voltage range, V_{OA} or V_{OB} (to AGND) . . . . . ±25 V
Peak input current . . . . . 10 µA
Operating free-air temperature range, T_A: TLC7628C . . . . . 0°C to +70°C
Storage temperature range, T_{stg} . . . . . −65°C to +150°C
Case temperature for 10 seconds, T_C: FN package . . . . . +260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package . . . . . +260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}		10.8		15.75	V
Reference voltage, V_{refA} or V_{refB}			±10		V
High-level input voltage, V_{IH}		2.4			V
Low-level input voltage, V_{IL}				0.8	V
$\overline{CS}$ setup time, $t_{su(CS)}$		50			ns
$\overline{CS}$ hold time, $t_{h(CS)}$ (see Figure 1)		0			ns
DAC select setup time, $t_{su(DAC)}$ (see Figure 1)		60			ns
DAC select hold time, $t_{h(DAC)}$ (see Figure 1)		10			ns
Data bus input setup time $t_{su(D)}$ (see Figure 1)		25			ns
Data bus input hold time $t_{h(D)}$ (see Figure 1)		10			ns
Pulse duration, $\overline{WR}$ low, $t_{w(WR)}$ (see Figure 1)		50			ns
Operating free-air temperature, T_A	TLC7628C	0		+70	°C

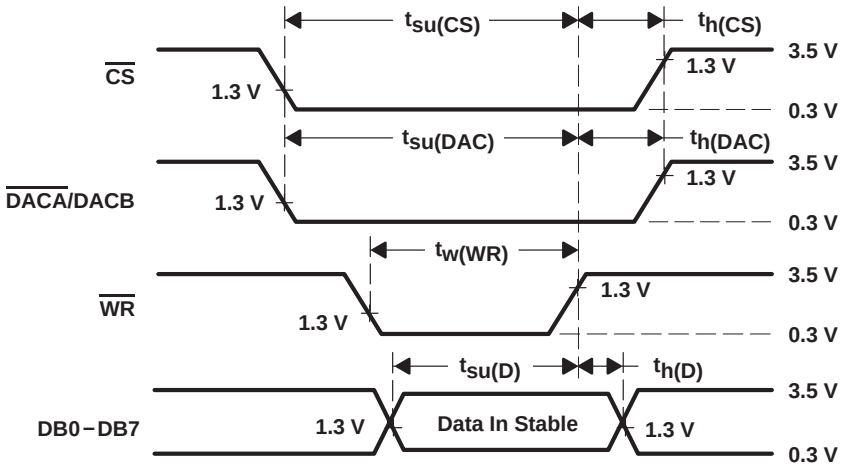
electrical characteristics over recommended ranges of operating free-air temperature and V_{DD}, $V_{refA} = V_{refB} = 10$ V, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	MAX	UNIT
I_{IH}	High-level input current		$V_I = V_{DD}$	Full range		10	µA
				25°C		1	
I_{IL}	Low-level input current		$V_I = 0$	Full range		−10	µA
				25°C		−1	
	Reference input impedance REFA or REFB to AGND				5	20	kΩ
I_{kg}	Output leakage current	OUTA	DAC data latch loaded with 00000000, V_{refA} = ±10 V	Full range		±200	nA
				25°C		±50	
		OUTB	DAC data latch loaded with 00000000, V_{refB} = ±10 V	Full range		±200	
				25°C		±50	
	Input resistance match (REFA to REFB)					±1%	
	DC supply sensitivity Δgain/ΔV_{DD}		ΔV_{DD} = ± 5 %	Full range		0.02	%/%
				25°C		0.01	
I_{DD}	Supply current	Quiescent	All digital inputs at V_{IH}min or V_{IL}max			2	mA
		Standby	All digital inputs at 0 V or V_{DD}	Full range		0.5	
				25°C		0.1	
C_i	Input capacitance	DB0−DB7				10	pF
		$\overline{WR}$, $\overline{CS}$, DACA/DACB				15	
C_o	Output capacitance (OUTA, OUTB)		DAC data latches loaded with 00000000			25	pF
			DAC data latches loaded with 11111111			60	

operating characteristics over recommended ranges of operating free-air temperature and V_{DD}, $V_{refA} = V_{refB} = 10$ V, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Linearity error						±1/2	LSB
Settling time (to 1/2 LSB)		See Note 1				100	ns
Gain error		See Note 2	Full range			±3	LSB
			25°C			±2	
AC feedthrough	REFA to OUTA	See Note 3	Full range			−65	dB
	REFB to OUTB		25°C			−75	
Temperature coefficient of gain						±0.0035	%FSR/°C
Propagation delay (from digital input to 90% of final analog output current)		See Note 4				80	ns
Channel-to-channel isolation	REFA to OUTB	See Note 5	25°C		80		dB
	REFB to OUTA	See Note 6	25°C		80		
Digital-to-analog glitch impulse area		Measured for code transition from 00000000 to 11111111, T_A = 25°C			330		nV•s
Digital crosstalk		Measured for code transition from 00000000 to 11111111, T_A = 25°C			60		nV•s
Harmonic distortion		V_i = 6 V, f = 1 kHz, T_A = 25°C			−85		dB

NOTES: 1. OUTA, OUTB load = 100 Ω, C_{ext} = 13 pF; $\overline{WR}$ and $\overline{CS}$ at 0 V; DB0−DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = V_{ref} − 1 LSB. Both DAC latches are loaded with 11111111.
3. V_{ref} = 20 V peak-to-peak, 10-kHz sine wave
4. $V_{refA} = V_{refB}$ = 10 V; OUTA/OUTB load = 100 Ω, C_{ext} = 13 pF; $\overline{WR}$ and $\overline{CS}$ at 0 V; DB0−DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
5. V_{refA} = 20 V peak-to-peak, 10-kHz sine wave; V_{refB} = 0
6. V_{refB} = 20 V peak-to-peak, 10-kHz sine wave; V_{refA} = 0

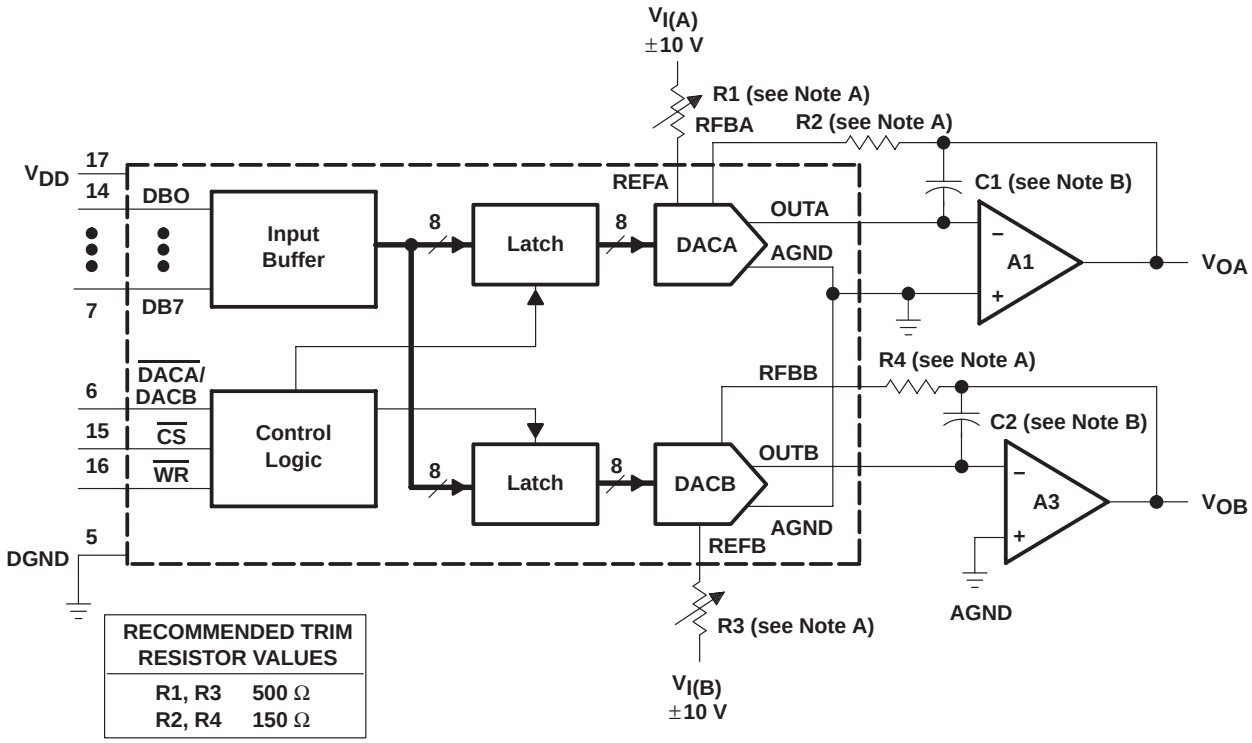


For all input signals, $t_r = t_f$ = 5 ns (10% to 90% points).

Figure 1. Setup and Hold Times

APPLICATION INFORMATION

This device is capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 2 and 3, respectively.

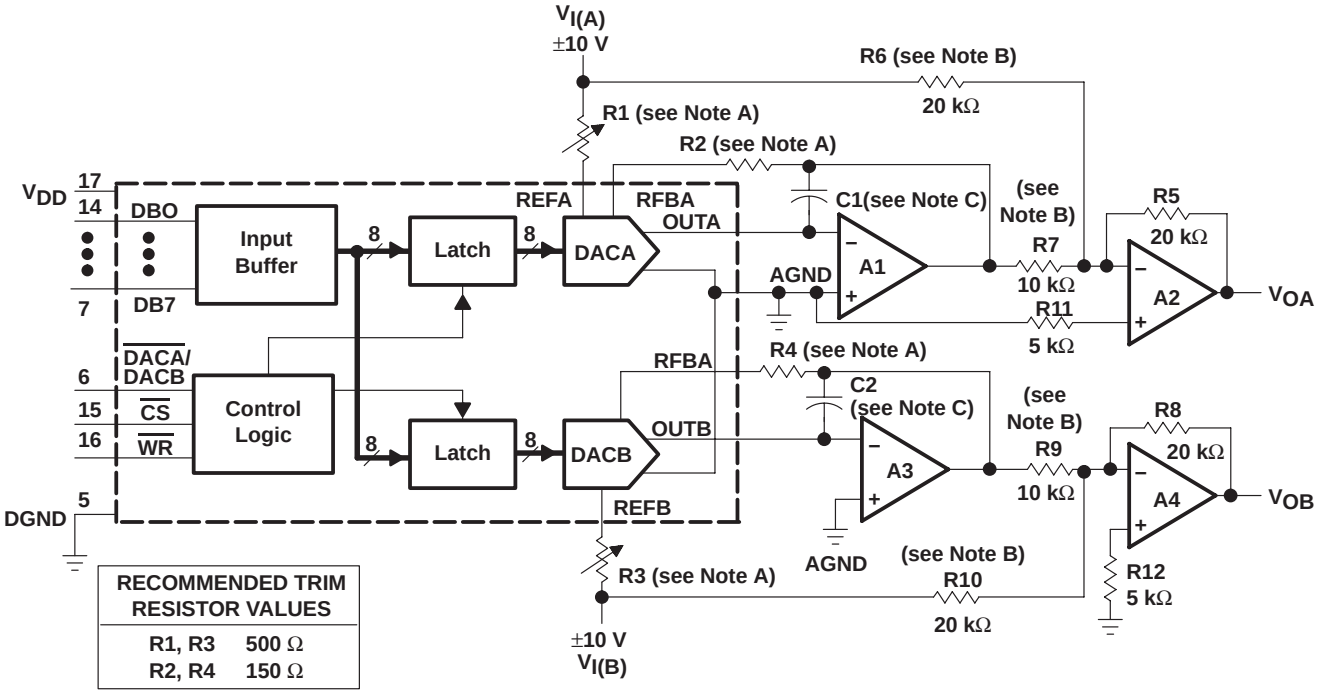


RECOMMENDED TRIM RESISTOR VALUES	
R1, R3	500 Ω
R2, R4	150 Ω

NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

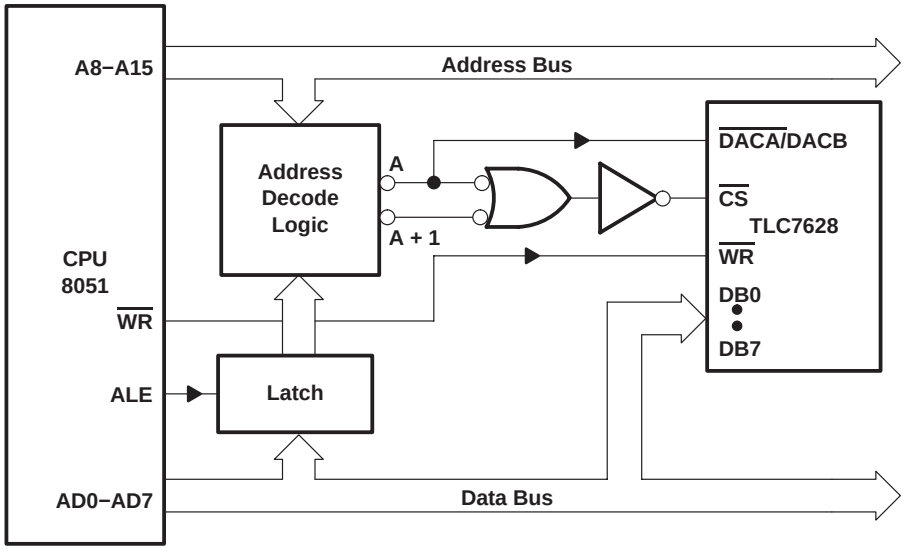
Figure 2. Unipolar Operation (2-Quadrant Multiplication)

APPLICATION INFORMATION



NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Adjust R1 for V_{OA} = 0 V with code 10000000 in DACA latch. Adjust R3 for V_{OB} = 0 V with 10000000 in DACB latch.
B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

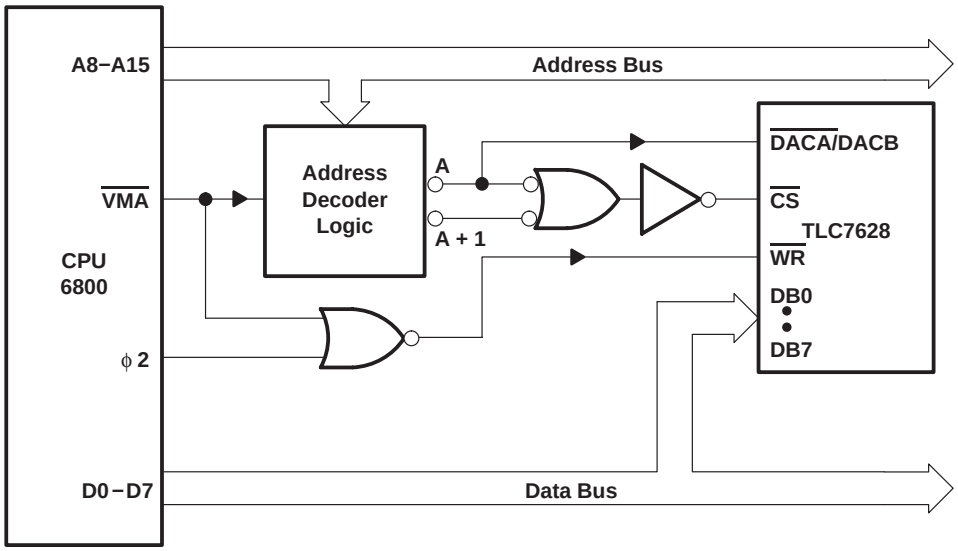
Figure 3. Bipolar Operation (4-Quadrant Operation)



NOTE D: A = decoded address for TLC7628 DACA
A + 1 = decoded address for TLC7628 DACB

Figure 4. TLC7628 — Intel 8051 Interface

APPLICATION INFORMATION



NOTE D: A = decoded address for TLC7628 DACA
A + 1 = decoded address for TLC7628 DACB

Figure 5. TLC7628 − 6800 Interface

voltage-mode operation

The current-multiplying DAC in the TLC7628C can be operated in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. An example of a current-multiplying DAC operating in voltage mode is shown in Figure 6. The relationship between the fixed input voltage and the analog output voltage is given by the following equation:

Analog output voltage = fixed input voltage (D/256)

where D = the digital input. In voltage-mode operation, these devices meet the following specification:

LINEARITY ERROR	TEST CONDITIONS	MIN	MAX	UNIT
Analog output voltage for REFA, REFB	V_{DD} = 12 V, OUTA or OUTB at 5 V, T_A = 25°C		1	LSB

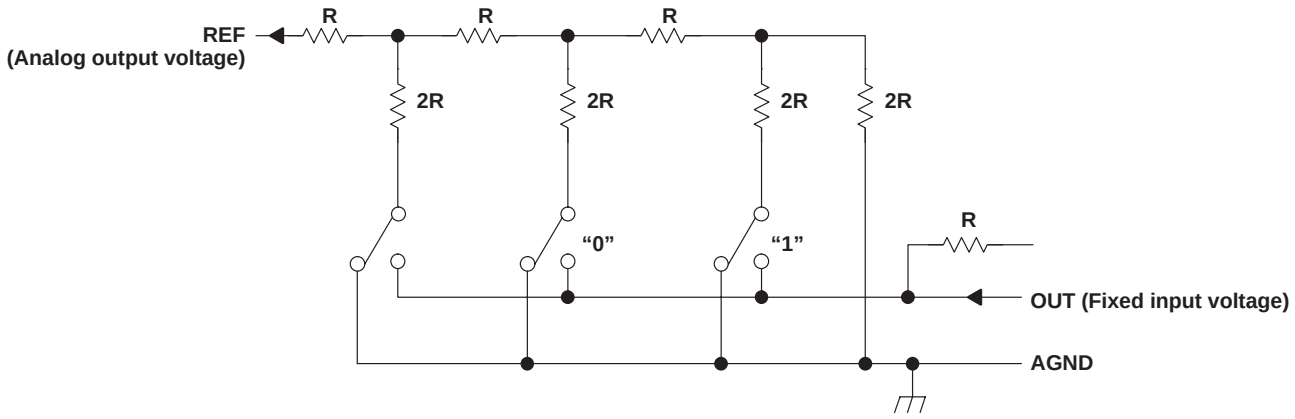


Figure 6. Current-Multiplying DAC Operating in Voltage Mode

PRINCIPLES OF OPERATION

This device contains two, identical, 8-bit, multiplying DACs: DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between the DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA or DACB with all digital inputs low is shown in Figure 7.

Figure 8 shows the DACA or DACB equivalent circuit. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. The C_o is caused by the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_o is 25 pF to 60 pF maximum. The equivalent output resistance (r_o) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

The TLC7628C interfaces to a microprocessor through the data bus, $\overline{CS}$, $\overline{WR}$, and $\overline{DACA}$/DACB control signals. When $\overline{CS}$ and $\overline{WR}$ are both low, the analog output on this device, specified by the $\overline{DACA}$/DACB control line, responds to the activity on the DB0−DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the $\overline{CS}$ signal or $\overline{WR}$ signal goes high, the data on the DB0−DB7 inputs are latched until the $\overline{CS}$ and $\overline{WR}$ signals go low again. When $\overline{CS}$ is high, the data inputs are disabled, regardless of the state of the $\overline{WR}$ signal.

The digital inputs of the TLC7628C provides TTL compatibility when operated from a supply voltage of 10.8 V to 15.75 V.

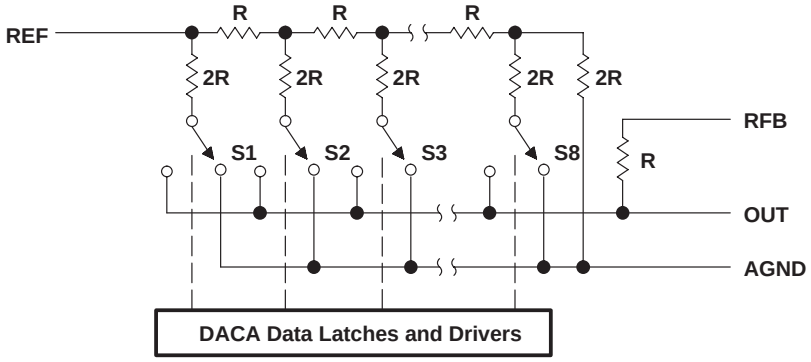


Figure 7. Simplified Functional Circuit for DACA or DACB

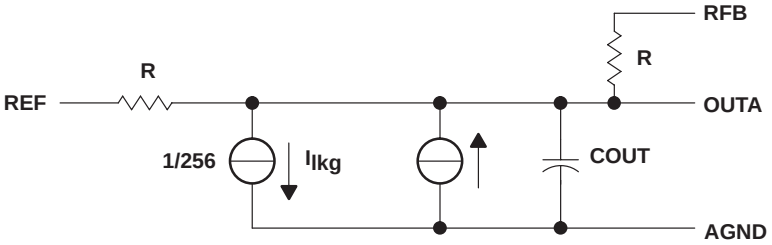


Figure 8. TLC7628 Equivalent Circuit for DACA or DACB

PRINCIPLES OF OPERATION

Table 1. Mode Selection Table

$\overline{DACA}$/DACB	$\overline{CS}$	$\overline{WR}$	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

L = low level, H = high level, X = don't care

Table 2. Unipolar Binary Code

DAC LATCH CONTENTS (see Note 7) MSB LSB	ANALOG OUTPUT
1 1 1 1 1 1 1 1	$-V_I$ (255/256)
1 0 0 0 0 0 0 1	$-V_I$ (129/256)
1 0 0 0 0 0 0 0	$-V_I$ (128/256) = $-V_i/2$
0 1 1 1 1 1 1 1	$-V_I$ (127/256)
0 0 0 0 0 0 0 1	$-V_I$ (1/256)
0 0 0 0 0 0 0 0	$-V_I$ (0/256) = 0

Table 3. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS (see Note 8) MSB LSB	ANALOG OUTPUT
1 1 1 1 1 1 1 1	V_I (127/128)
1 0 0 0 0 0 0 1	V_I (1/128)
1 0 0 0 0 0 0 0	0 V
0 1 1 1 1 1 1 1	$-V_I$ (1/128)
0 0 0 0 0 0 0 1	$-V_I$ (127/128)
0 0 0 0 0 0 0 0	$-V_I$ (128/128)

NOTES: 7. 1 LSB = $(2^{-8})V_I$
8. 1 LSB = $(2^{-7})V_I$

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC7628CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C	Samples
TLC7628CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C	Samples
TLC7628CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C	Samples
TLC7628CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C	Samples
TLC7628CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC7628CN	Samples
TLC7628IN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

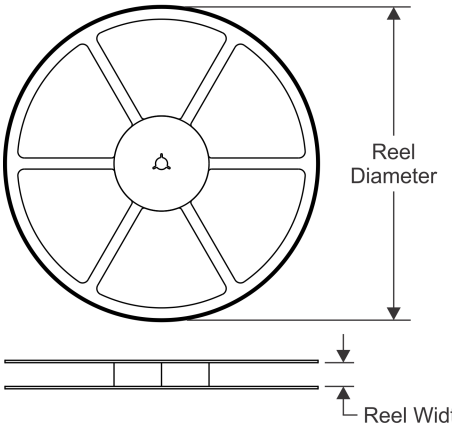
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

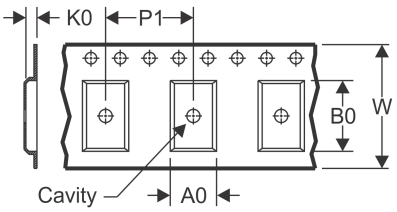
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

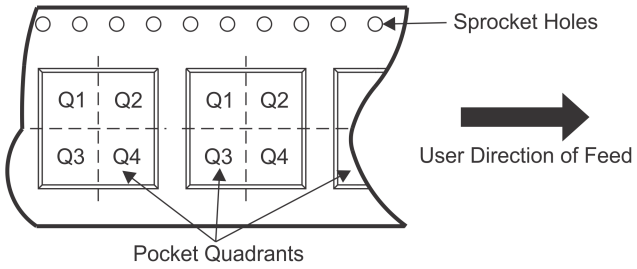


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

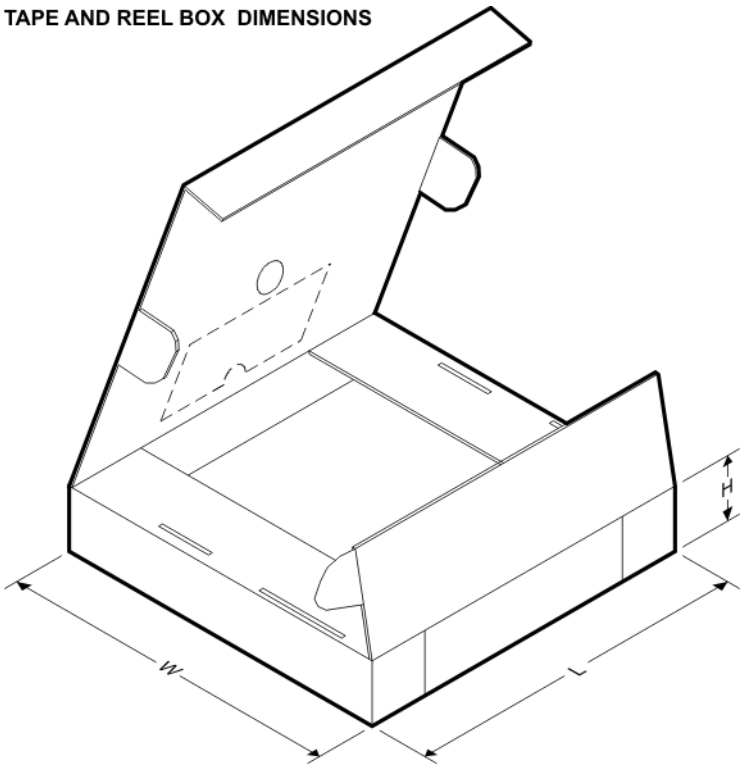
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7628CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



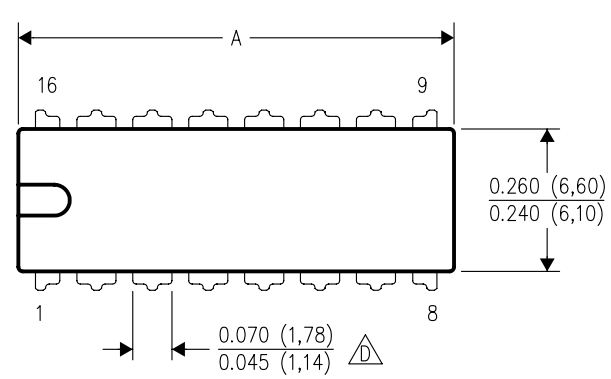
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7628CDWR	SOIC	DW	20	2000	367.0	367.0	45.0

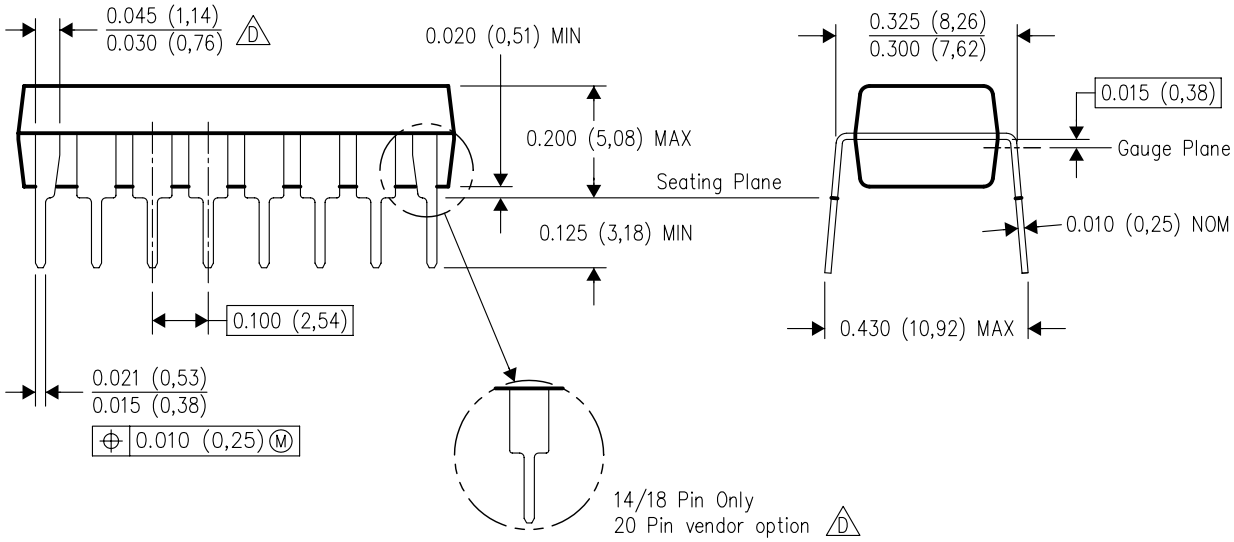
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

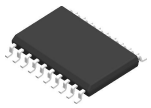


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

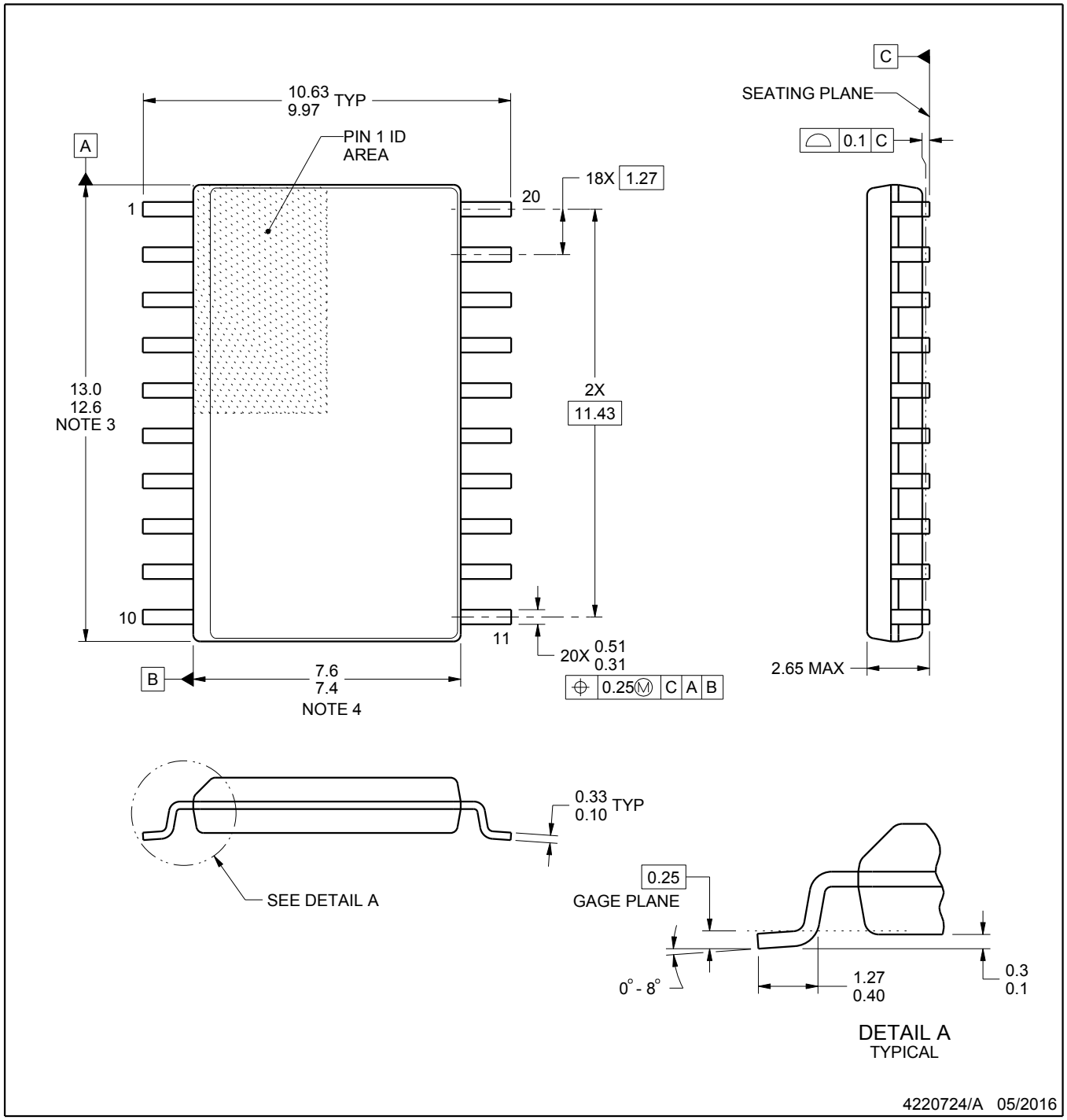


PACKAGE OUTLINE

DW0020A

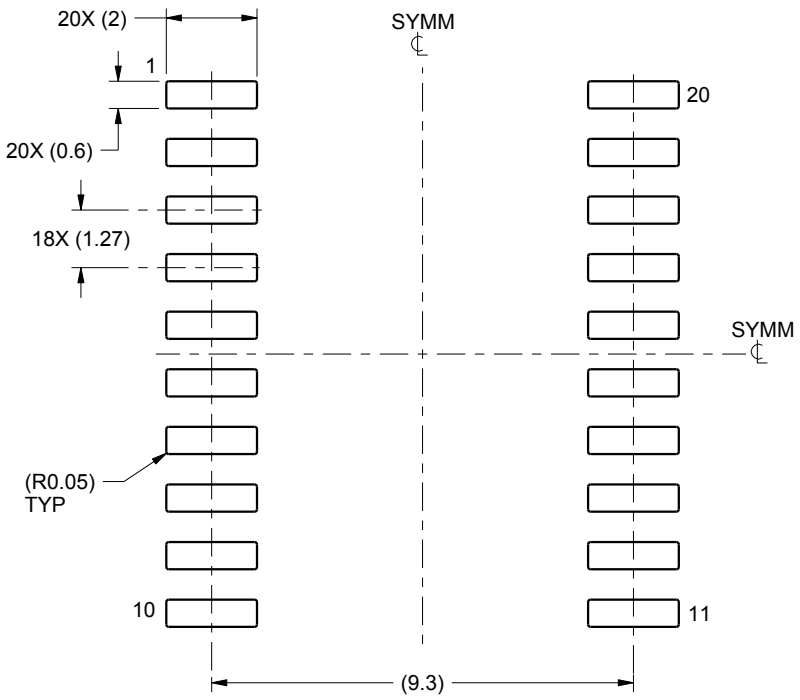
SOIC - 2.65 mm max height

SOIC

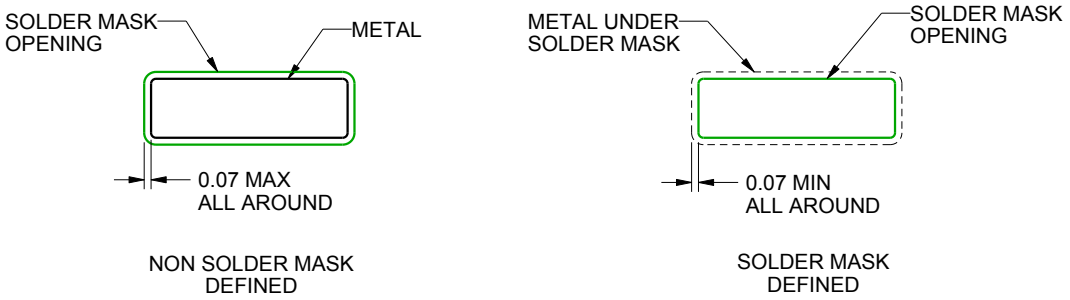


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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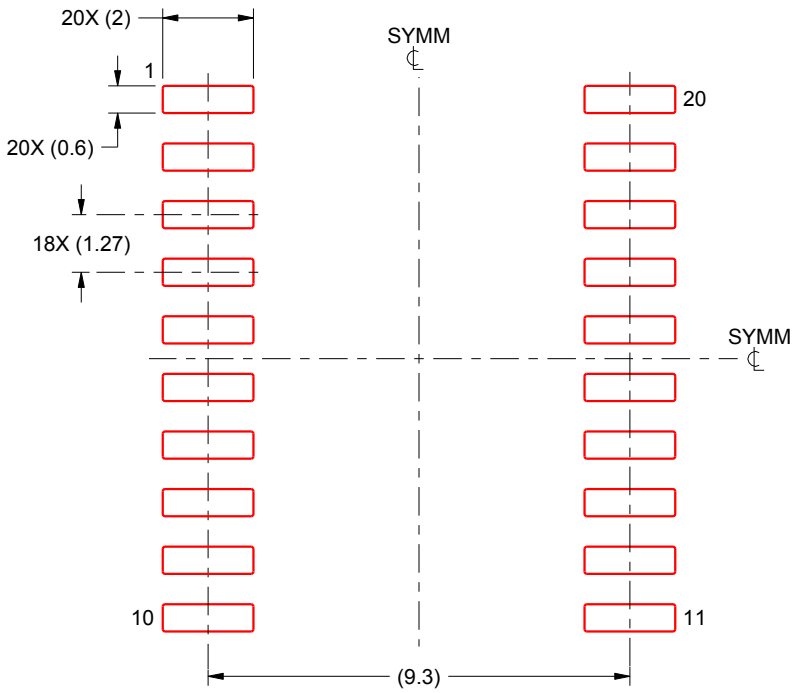
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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